



# 200526786 BGM13P/MGM13P Datasheet v1.2 for MGM13P and v1.21 for BGM13P

**PCN Issue Date:** 5/26/2020

**Effective Date:** 9/1/2020

**PCN Type:** Datasheet

## Description of Change

Silicon Labs is pleased to announce new data sheet versions v1.2 for MGM13P and v1.21 for BGM13P. The updates include new package and landing pattern dimensions and addition of the certification ID in Korea

For the BGM13P compared to the previous datasheet version 1.2, the changes in v1.21 datasheet are

- In the front page block diagram, the lowest energy mode for LETIMER updated.
- Removed Wake On Radio references wherever applicable since this feature is not supported by the software.
- In section 3.6.4, Low Energy Timer (LETIMER) lowest energy mode updated
- PTI description in section 7.3.2 Packet Trace Interface (PTI) updated
- In section, 9.1 package outline updated.
- In sections 9.2, the dimensions for recommended PCB Land Pattern updated
- In sectiond 9.3, package marking images and description updated
- The text in section 11.3 about CE marking updated
- In section 11.7 KC South Korea certification updated

For the MGM13P v1.2 the changes are

- In the front page block diagram, the lowest energy mode for LETIMER updated.
- Removed Wake On Radio references wherever applicable since this feature is not supported by the software.
- Removed multiprotocol from protocol stack Table 2.1 Ordering Information on page 3.
- In section 3.2, Radio overview updated.
- In section 3.6.4 Low Energy Timer (LETIMER) lowest energy mode updated.
- DCDC Low Power Mode configuration note in Table 4.4 and Current Consumption 3.3 V using DC-DC Converter updated on page 21.
- Wording in Table 4.23 Voltage Monitor (VMON) on page 33 updated.
- VDAC test conditions for EM2 current consumption Table 4.26 Digital to Analog Converter (VDAC) updated on page 39.
- Register name IREFPROG for CSEN test conditions Table 4.28 Capacitive Sense (CSEN) updated on page 44.
- Insection 7.3.2, PTI description Packet Trace Interface (PTI).
- Package drawing and specifications in section 9.1 Package Outline updated.
- In section 9.2, the dimensions of recommended PCB land pattern updated.
- In section 9.3, Package Marking images and description updated.
- Additional text in section 10, Soldering Recommendations.
- The text in section 11.3 CE certification updated.
- Added Certification number in section 11.7 KC South Korea certification.
- Minor wording change regarding peripheral modules

## Reason for Change

Datasheet revision update. See description section above on the changed details.

## Impact on Form, Fit, Function, Quality, Reliability

There is no impact on Form, Function, Quality and Reliability. Customer is advised to review the change in recommended Land Pattern in the datasheet.

## Product Identification

Existing Part #

BGM13P22F512GA-V2  
BGM13P22F512GA-V2R  
BGM13P22F512GE-V2  
BGM13P22F512GE-V2R  
BGM13P32F512GA-V2  
BGM13P32F512GA-V2R  
BGM13P32F512GE-V2  
BGM13P32F512GE-V2R  
BGM13S22F512GA-V3  
BGM13S22F512GA-V3R  
BGM13S22F512GN-V2  
BGM13S22F512GN-V2R  
BGM13S22F512GN-V3  
BGM13S22F512GN-V3R  
BGM13S32F512GA-V3  
BGM13S32F512GA-V3R  
BGM13S32F512GN-V2  
BGM13S32F512GN-V2R  
BGM13S32F512GN-V3  
BGM13S32F512GN-V3R  
MGM13P02F512GA-V2  
MGM13P02F512GA-V2R  
MGM13P02F512GE-V2  
MGM13P02F512GE-V2R  
MGM13P12F512GA-V2  
MGM13P12F512GA-V2R  
MGM13P12F512GE-V2  
MGM13P12F512GE-V2R  
MGM13S02F512GA-V2  
MGM13S02F512GA-V2R  
MGM13S02F512GA-V3  
MGM13S02F512GA-V3R  
MGM13S02F512GN-V2  
MGM13S02F512GN-V2R  
MGM13S02F512GN-V3  
MGM13S02F512GN-V3R  
MGM13S12F512GA-V2  
MGM13S12F512GA-V2R  
MGM13S12F512GA-V3  
MGM13S12F512GA-V3R  
MGM13S12F512GN-V2  
MGM13S12F512GN-V2R  
MGM13S12F512GN-V3  
MGM13S12F512GN-V3R

**Last Date of Unchanged Product:** 9/1/2020

### Qualification Samples

Available upon request.

### Customer Response

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change, Ref. JEDEC-J-STD-046.

To request further data or inquire about this notification, please contact your Silicon Labs sales representative. A list of Silicon Labs sales representatives is available at <http://www.silabs.com>.

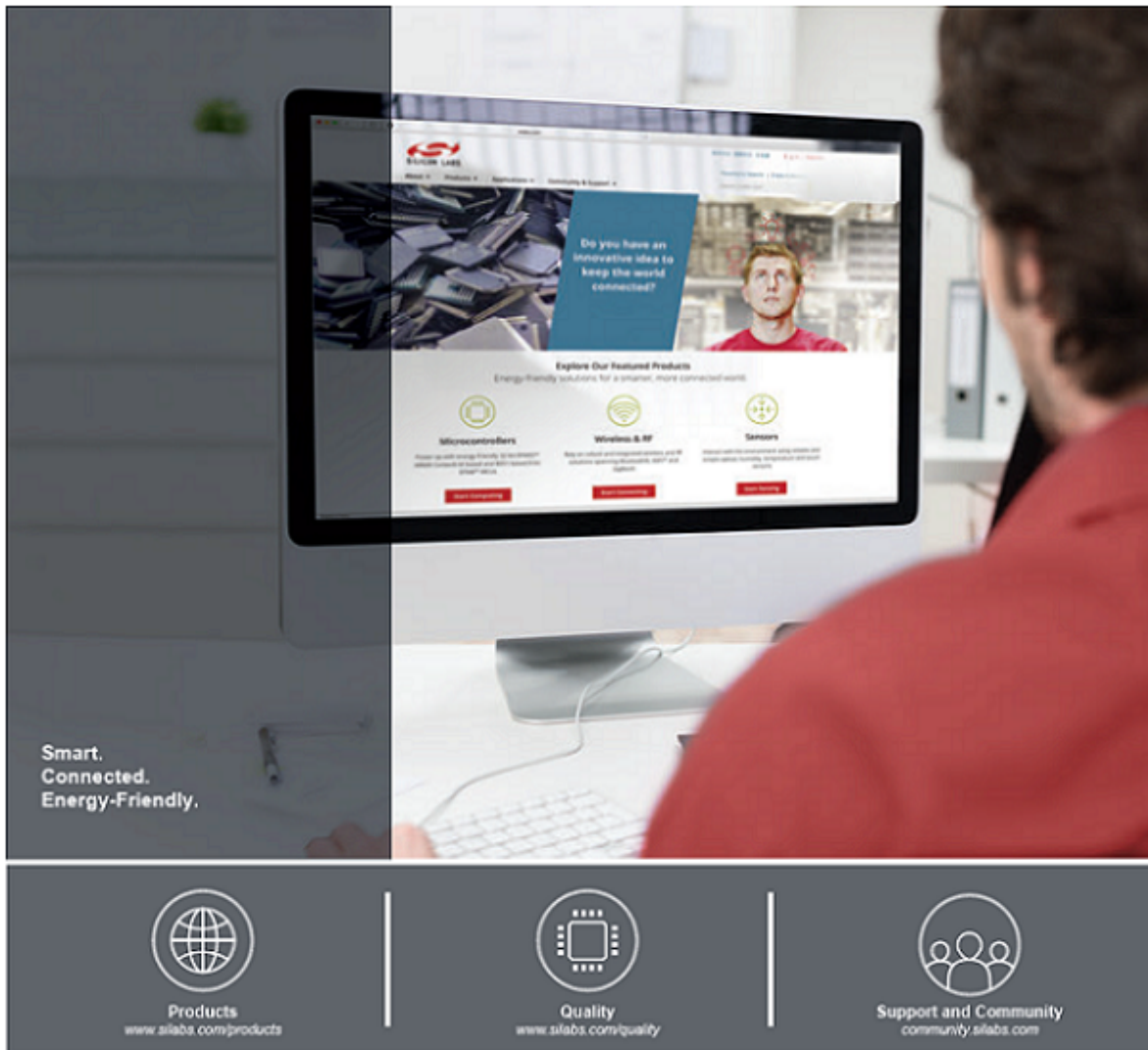
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### Qualification Data

N/A



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